### SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SYCK08

Super Bright Yellow

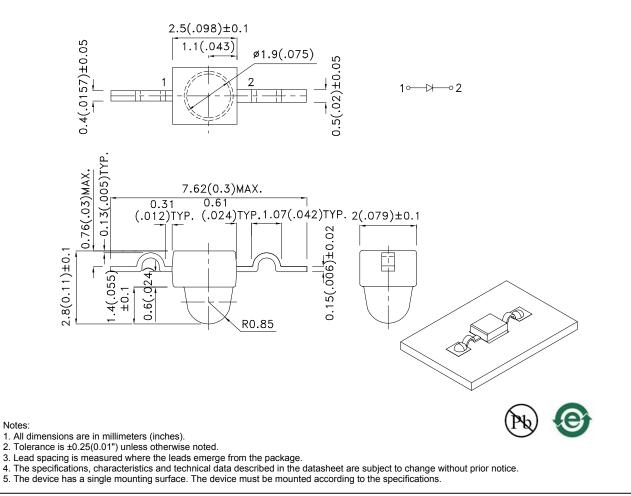
#### Features

- Subminiature package.
- Yoke lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

#### Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

#### Package Dimensions



SPEC NO: DSAD1273 APPROVED: WYNEC REV NO: V.8B CHECKED: Allen Liu DATE: APR/18/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1202000719

## Salaction Guida

Part No.	Dice	Lens Type	lv (mo @ 20	/ <b>- -</b>	Viewing Angle [1]	
			Min.	Тур.	201/2	
AM2520SYCK08	Super Bright Yellow (InGaAIP)	Water Clear	1300	2300	20°	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	I⊧=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I⊧=20mA
lr	Reverse Current	Super Bright Yellow		10	uA	Vr=5V

Notes:

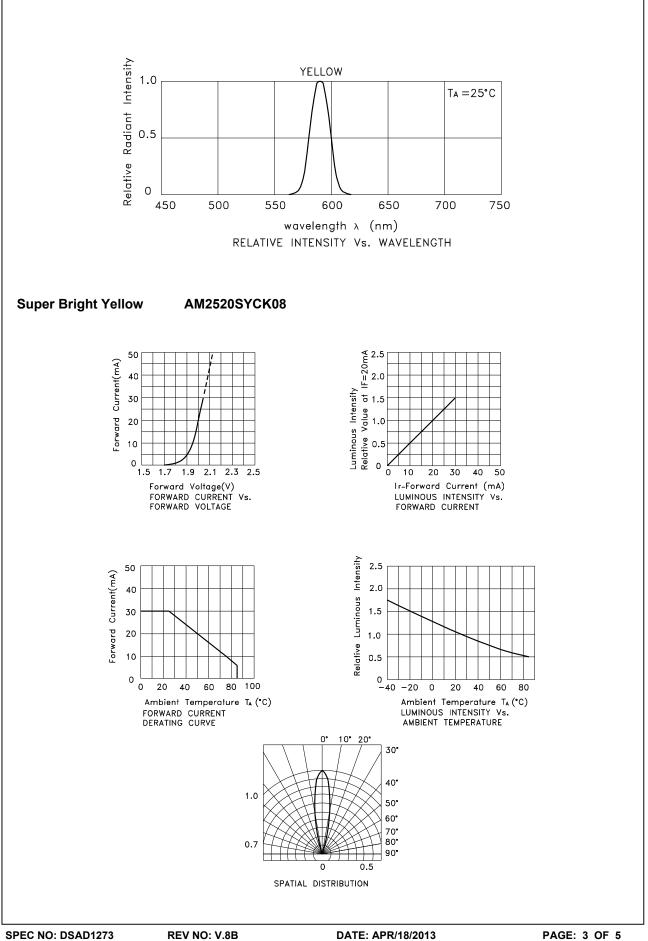
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

### Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow			
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	175	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

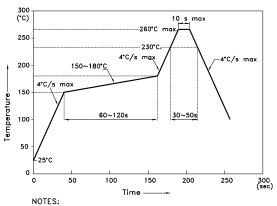
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## AM2520SYCK08

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

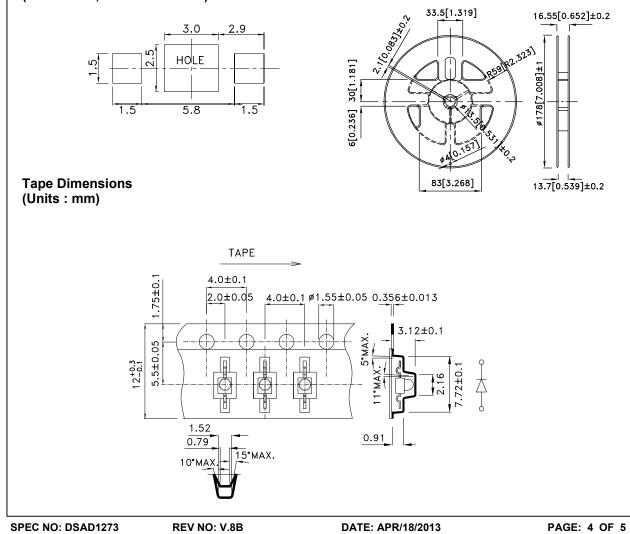
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature  $245^{\circ}C(+/-5^{\circ}C)$ . The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

**Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1)

### **Reel Dimension**



**APPROVED: WYNEC** 

**CHECKED: Allen Liu** 

**DRAWN: F.Cui** 

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